# Thermal TIG0350C 导热硅脂

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**Thermal TIG0350C** 是一种具有低粘度，低热阻的导热硅脂，可采用丝网印刷的方式涂覆在发热器件或者散热器表面，装配后可以跟界面形成良好的润湿，降低系统的接触热阻，从而提高散热效率。该产品可在常温下短期储存，并在高温下固化形成具有弹性的垫片.

**Thermal TIG0350C** is a kind of thermal grease material with low viscosity and low thermal resistance. The material can be applied on heating devices and heat spreader surfaces by screen printing. Due to good wetting between the interfaces after assembly, the contact thermal resistance will be substantially reduced to improve heat dissipation efficiency. This product can be stored at RT for short-term and cured at elevated temperature to form elastic pad.

**Features 特性**

- Low Thermal Resistance 低热阻
- Low Viscosity 低粘度
- High Reliability 高可靠性
- Screen Printing 丝网印刷

**Applications 产品应用**

- Laptop CPU 笔记本电脑 CPU
- Communication equipment 通讯设备
- Power supply controller 电源控制系统
- ADAS 智能驾驶系统

| Property 特性 | Typical Value 典型值 | Unit 单位 | Test Method 测试方法 |
|---|---|---|---|
| **Composition 主要成分** | Silicone Filled with Thermal Powder 硅胶&导热粉体 | | — |
| **Color 颜色** | Blue 蓝色 | — | Visual 目视 |
| **Thermal Conductivity 导热系数** | 3.5 | W/m·K | ASTM D5470 |
| **Thermal Resistance 热阻** | 0.13 @ 40Psi | °C.cm$^2$/W | ASTM D5470 |
| **Viscosity 粘度@1s$^{-1}$** | 350 | Pa.s | ASTM D2196 |
| **Bond-line Thickness (BLT) 界面结合厚度** | 25 | μm | — |
| **Density 密度** | 3.30 | g/cm$^3$ | ASTM D792 |
| **Hardness 硬度（Shore A）** | 70 | — | ASTM D2240 |
| **Temperature Range 耐温范围** | -40 - 150 | °C | — |
| **Breakdown Voltage 击穿强度** | 6.0 | KV/mm | ASTM D149 |
| **Volume Resistivity 体积电阻率** | $10^{13}$ | Ω.cm | ASTM D257 |
| **RoHS Compliance 合规性** | YES | — | — |
| **Shelf Life 保存期** | 6 | Month | ≤-10°C，未启封 |